

ABSTRACT OF THE DISCLOSURE

A thermal enhance package mainly comprises a chip, a substrate unit, a heat spreader unit and a plurality of pellets. The chip is disposed above the substrate unit and electrically connected to the substrate unit, and an encapsulation unit encapsulates the chip, the substrate unit, the heat spreader unit and the pellets. Therein the pellets are formed on the substrate unit and connect the substrate unit and the heat spreader unit. Thus the heat arisen out of the chip can be transmitted to the heat spreader unit not only through the encapsulation unit but also the pellets. Moreover, the substrate unit has at least one grounding contact connecting to one of the pellets so as to provide the thermal enhance package a good shielding. In addition, a method for manufacturing the thermal enhance package is also provided.